

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4513885

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YASUMASA YAMANE	07/04/2017
MOTOMU KURATA	07/04/2017
RYOTA HODO	07/05/2017
TAKAHISA ISHIYAMA	07/04/2017
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15652299
CORRESPONDENCE DATA	
Fax Number:	(877)769-7945
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(202) 783-5070
Email:	APSI@fr.com
Correspondent Name:	JOHN F. HAYDEN
Address Line 1:	FISH & RICHARDSON P.C.
Address Line 2:	P.O.BOX 1022
Address Line 4:	MINNEAPOLIS, MINNESOTA 55440-1022
ATTORNEY DOCKET NUMBER:	12732-1854001
NAME OF SUBMITTER:	JANELLE A. JACKSON
SIGNATURE:	/Janelle A. Jackson/
DATE SIGNED:	07/21/2017
Total Attachments: 2	
source=12732-1854001 Assignment#page1.tif	
source=12732-1854001 Assignment#page2.tif	

ASSIGNMENT

For valuable consideration, We, Yasumasa YAMANE of Atsugi, Kanagawa, Japan, Motomu KURATA of Isehara, Kanagawa, Japan, Ryota HODO of Atsugi, Kanagawa, Japan and Takahisa ISHIYAMA of Atsugi, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE, filed July 18, 2017, and assigned U.S. Serial Number 15/652,299, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Yasumasa YAMANE
Name: Yasumasa YAMANE
Date: 07/04/2017

Signature Motomu KURATA
Name: Motomu KURATA
Date: 07/04/2017

Signature Ryota HODO
Name: Ryota HODO
Date: 07/05/2017

Signatur Takahisa ISHIYAMA
Name: Takahisa ISHIYAMA
Date: 07/04/2017